

Mads Brincker

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/4480018/publications.pdf>

Version: 2024-02-01

9
papers

69
citations

1684188
5
h-index

1588992
8
g-index

9
all docs

9
docs citations

9
times ranked

73
citing authors

#	ARTICLE	IF	CITATIONS
1	Strength and reliability of low temperature transient liquid phase bonded Cu Sn Cu interconnects. Microelectronics Reliability, 2017, 76-77, 378-382.	1.7	23
2	Effects of thermal cycling on aluminum metallization of power diodes. Microelectronics Reliability, 2015, 55, 1988-1991.	1.7	13
3	Microstructured gradient-index lenses for THz photoconductive antennas. AIP Advances, 2016, 6, .	1.3	9
4	Comparative Study of Al Metallization Degradation in Power Diodes Under Passive and Active Thermal Cycling. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 2073-2080.	2.5	7
5	Thermo-mechanically induced texture evolution and micro-structural change of aluminum metallization. Journal of Materials Science: Materials in Electronics, 2018, 29, 3898-3904.	2.2	6
6	Mechanisms of metallization degradation in high power diodes. Microelectronics Reliability, 2016, 64, 489-493.	1.7	5
7	Low temperature transient liquid phase bonded Cu-Sn-Mo and Cu-Sn-Ag-Mo interconnects " A novel approach for hybrid metal baseplates. Microelectronics Reliability, 2018, 88-90, 774-778.	1.7	5
8	Tunable local excitation of surface plasmon polaritons by sum-frequency generation in ZnO nanowires. Optics Communications, 2015, 356, 109-112.	2.1	1
9	Theoretical analysis of microstructured gradient-index lens for THz photonics using Greens function integral equation methods. , 2016, , .		0